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Intel - 10AS032H4F35E3LG Datasheet



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Embedded - System On Chip (SoC): The Heart of Modern Embedded Systems

Embedded - System On Chip (SoC) refers to an integrated circuit that consolidates all the essential components of a computer system into a single chip. This includes a microprocessor, memory, and other peripherals, all packed into one compact and efficient package. SoCs are designed to provide a complete computing solution, optimizing both space and power consumption, making them ideal for a wide range of embedded applications.

What are **Embedded - System On Chip (SoC)**?

System On Chip (SoC) integrates multiple functions of a computer or electronic system onto a single chip. Unlike traditional multi-chip solutions. SoCs combine a central

Details

| Product Status | Active |
|-------------------------|--|
| Architecture | MCU, FPGA |
| Core Processor | Dual ARM® Cortex®-A9 MPCore ^{m} with CoreSight ^{m} |
| Flash Size | - |
| RAM Size | 256KB |
| Peripherals | DMA, POR, WDT |
| Connectivity | EBI/EMI, Ethernet, I ² C, MMC/SD/SDIO, SPI, UART/USART, USB OTG |
| Speed | 1.5GHz |
| Primary Attributes | FPGA - 320K Logic Elements |
| Operating Temperature | 0°C ~ 100°C (TJ) |
| Package / Case | 1152-BBGA, FCBGA |
| Supplier Device Package | 1152-FBGA, FC (35x35) |
| Purchase URL | https://www.e-xfl.com/product-detail/intel/10as032h4f35e3lg |
| | |

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong



| Feature | Description | |
|--|--|---------|
| Low-power serial transceivers | Continuous operating range: Intel Arria 10 GX—1 Gbps to 17.4 Gbps Intel Arria 10 GT—1 Gbps to 25.8 Gbps Backplane support: Intel Arria 10 GX—up to 12.5 Intel Arria 10 GT—up to 12.5 Extended range down to 125 Mbps with oversampling ATX transmit PLLs with user-configurable fractional synthesis capability Electronic Dispersion Compensation (EDC) support for XFP, SFP+, QSFP, and CFP optical module Adaptive linear and decision feedback equalization Transmitter pre-emphasis and de-emphasis Dynamic partial reconfiguration of individual transceiver channels | |
| HPS (Intel Arria 10 SX devices only) | Processor and system • Dual-core ARM Cortex-A9 MPCore processor—1.2 GHz CPU with 1.5 GHz overdrive capability • 256 KB on-chip RAM and 64 KB on-chip ROM • System peripherals—general-purpose timers, watchdog timers, di memory access (DMA) controller, FPGA configuration manager, ar clock and reset managers • Security features—anti-tamper, secure boot, Advanced Encryptior Standard (AES) and authentication (SHA) • ARM CoreSight* JTAG debug access port, trace port, and on-chip trace storage | nd n |
| | External interfaces Hard memory interface—Hard memory controller (2,400 Mbps DE and 2,133 Mbps DDR3), Quad serial peripheral interface (QSPI) fl controller, NAND flash controller, direct memory access (DMA) controller, Secure Digital/MultiMediaCard (SD/MMC) controller Communication interface—10/100/1000 Ethernet media access control (MAC), USB On-The-GO (OTG) controllers, I²C controllers, UART 16550, serial peripheral interface (SPI), and up to 62 HPS GPIO interfaces (48 direct-share I/Os) | lash |
| | Interconnects to core • High-performance ARM AMBA* AXI bus bridges that support simultaneous read and write • HPS-FPGA bridges—include the FPGA-to-HPS, HPS-to-FPGA, and lightweight HPS-to-FPGA bridges that allow the FPGA fabric to iss transactions to slaves in the HPS, and vice versa • Configuration bridge that allows HPS configuration manager to configure the core logic via dedicated 32-bit configuration port • FPGA-to-HPS SDRAM controller bridge—provides configuration interfaces for the multiport front end (MPFE) of the HPS SDRAM controller | |
| Configuration | Tamper protection—comprehensive design protection to protect your valuable IP investment Enhanced 256-bit advanced encryption standard (AES) design security with authentication Configuration via protocol (CvP) using PCIe Gen1, Gen2, or Gen3 | |
| | continue | d |

 $^{^{(2)}\,}$ Intel Arria 10 devices support this external memory interface using hard PHY with soft memory controller.



| Feature | Description |
|--------------------|---|
| | Dynamic reconfiguration of the transceivers and PLLs Fine-grained partial reconfiguration of the core fabric Active Serial x4 Interface |
| Power management | SmartVID Low static power device options Programmable Power Technology Intel Quartus Prime integrated power analysis |
| Software and tools | Intel Quartus Prime design suite Transceiver toolkit Platform Designer system integration tool DSP Builder for Intel FPGAs OpenCL[™] support Intel SoC FPGA Embedded Design Suite (EDS) |

Related Information

Intel Arria 10 Transceiver PHY Overview Provides details on Intel Arria 10 transceivers.

Intel Arria 10 Device Variants and Packages

Table 4. Device Variants for the Intel Arria 10 Device Family

| Variant | Description |
|-------------------|---|
| Intel Arria 10 GX | FPGA featuring 17.4 Gbps transceivers for short reach applications with 12.5 backplane driving capability. |
| Intel Arria 10 GT | FPGA featuring: 17.4 Gbps transceivers for short reach applications with 12.5 backplane driving capability. 25.8 Gbps transceivers for supporting CAUI-4 and CEI-25G applications with CFP2 and CFP4 modules. |
| Intel Arria 10 SX | SoC integrating ARM-based HPS and FPGA featuring 17.4 Gbps transceivers for short reach applications with 12.5 backplane driving capability. |

Intel Arria 10 GX

This section provides the available options, maximum resource counts, and package plan for the Intel Arria 10 GX devices.

The information in this section is correct at the time of publication. For the latest information and to get more details, refer to the Intel FPGA Product Selector.

Related Information

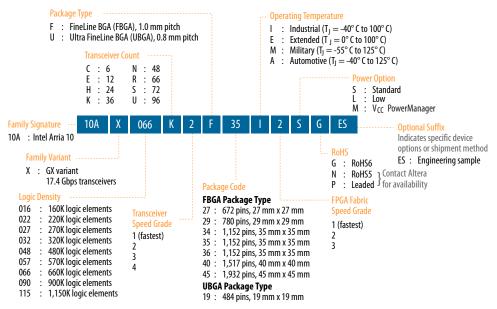
Intel FPGA Product Selector

Provides the latest information on Intel products.



Available Options

Figure 1. Sample Ordering Code and Available Options for Intel Arria 10 GX Devices



Related Information

Transceiver Performance for Intel Arria 10 GX/SX Devices Provides more information about the transceiver speed grade.



ES : Engineering sample

RoHS

FPGA Fabric

Speed Grade

1 (fastest)

2 3

G : RoHS6 N : RoHS5 Contact Intel P : Leaded for availability

Available Options

Family Variant

090 : 900K logic elements 115 : 1,150K logic elements

25.8 Gbps transceivers

Transceiver

1 (fastest)

2

Speed Grade

T : GT variant

Logic Density



Package Code

45 : 1,932 pins, 45 mm x 45 mm

Figure 2. Sample Ordering Code and Available Options for Intel Arria 10 GT Devices



Maximum Resources

Table 10. Maximum Resource Counts for Intel Arria 10 GT Devices

| Reso | urce | Produ | ct Line |
|------------------------------|----------------------|-----------|-------------------|
| | | GT 900 | GT 1150 |
| Logic Elements (LE) (K) | | 900 | 1,150 |
| ALM | | 339,620 | 427,200 |
| Register | | 1,358,480 | 1,708,800 |
| Memory (Kb) | M20K | 48,460 | 54,260 |
| | MLAB | 9,386 | 12,984 |
| Variable-precision DSP Block | | 1,518 | 1,518 |
| 18 x 19 Multiplier | | 3,036 | 3,036 |
| PLL | Fractional Synthesis | 32 | 32 |
| | I/O | 16 | 16 |
| Transceiver | 17.4 Gbps | 72 (5) | 72 ⁽⁵⁾ |
| | 25.8 Gbps | 6 | 6 |
| GPIO ⁽⁶⁾ | | 624 | 624 |
| LVDS Pair ⁽⁷⁾ | | 312 | 312 |
| PCIe Hard IP Block | | 4 | 4 |
| Hard Memory Controller | | 16 | 16 |

Related Information

Intel Arria 10 GT Channel Usage

Configuring GT/GX channels in Intel Arria 10 GT devices.

Package Plan

Table 11.Package Plan for Intel Arria 10 GT Devices

Refer to I/O and High Speed I/O in Intel Arria 10 Devices chapter for the number of 3 V I/O, LVDS I/O, and LVDS channels in each device package.

| Product Line | SF45 (45 mm × 45 mm, 1932-pin FBGA) | | | | |
|--------------|--|----------|------|--|--|
| | 3 V I/O | LVDS I/O | XCVR | | |
| GT 900 | — | 624 | 72 | | |
| GT 1150 | _ | 624 | 72 | | |

⁽⁵⁾ If all 6 GT channels are in use, 12 of the GX channels are not usable.

⁽⁶⁾ The number of GPIOs does not include transceiver I/Os. In the Intel Quartus Prime software, the number of user I/Os includes transceiver I/Os.

⁽⁷⁾ Each LVDS I/O pair can be used as differential input or output.



Maximum Resources

Table 12. Maximum Resource Counts for Intel Arria 10 SX Devices

| Resource | | | | I | Product Line | | | |
|------------------------------|-------------------------|---------|---------|---------|--------------|---------|---------|-----------|
| | | SX 160 | SX 220 | SX 270 | SX 320 | SX 480 | SX 570 | SX 660 |
| Logic Elements | s (LE) (K) | 160 | 220 | 270 | 320 | 480 | 570 | 660 |
| ALM | | 61,510 | 80,330 | 101,620 | 119,900 | 183,590 | 217,080 | 251,680 |
| Register | | 246,040 | 321,320 | 406,480 | 479,600 | 734,360 | 868,320 | 1,006,720 |
| Memory (Kb) | M20K | 8,800 | 11,740 | 15,000 | 17,820 | 28,620 | 36,000 | 42,620 |
| | MLAB | 1,050 | 1,690 | 2,452 | 2,727 | 4,164 | 5,096 | 5,788 |
| Variable-precision DSP Block | | 156 | 192 | 830 | 985 | 1,368 | 1,523 | 1,687 |
| 18 x 19 Multip | lier | 312 | 384 | 1,660 | 1,970 | 2,736 | 3,046 | 3,374 |
| PLL | Fractional Synthesis | 6 | 6 | 8 | 8 | 12 | 16 | 16 |
| | I/O | 6 | 6 | 8 | 8 | 12 | 16 | 16 |
| 17.4 Gbps Tra | nsceiver | 12 | 12 | 24 | 24 | 36 | 48 | 48 |
| GPIO ⁽⁸⁾ | | 288 | 288 | 384 | 384 | 492 | 696 | 696 |
| LVDS Pair ⁽⁹⁾ | | 120 | 120 | 168 | 168 | 174 | 324 | 324 |
| PCIe Hard IP Block | | 1 | 1 | 2 | 2 | 2 | 2 | 2 |
| Hard Memory Controller | | 6 | 6 | 8 | 8 | 12 | 16 | 16 |
| ARM Cortex-As Processor | 9 MPCore | Yes | Yes | Yes | Yes | Yes | Yes | Yes |

Package Plan

Table 13.Package Plan for Intel Arria 10 SX Devices (U19, F27, F29, and F34)

Refer to I/O and High Speed I/O in Intel Arria 10 Devices chapter for the number of 3 V I/O, LVDS I/O, and LVDS channels in each device package.

| Product Line | U19 (19 mm × 19 mm, 484-pin UBGA) | | F27 (27 mm × 27 mm, 672-pin FBGA) | | F29 (29 mm × 29 mm, 780-pin FBGA) | | F34 (35 mm × 35 mm, 1152-pin FBGA) | | | | | |
|--------------|---|-------------|---|------------|---|------|--|-------------|------|------------|-------------|------|
| | 3 V I/O | LVDS I/O | XCVR | 3 V I/O | LVDS I/O | XCVR | 3 V I/O | LVDS I/O | XCVR | 3 V I/O | LVDS I/O | XCVR |
| SX 160 | 48 | 144 | 6 | 48 | 192 | 12 | 48 | 240 | 12 | _ | - | - |
| SX 220 | 48 | 144 | 6 | 48 | 192 | 12 | 48 | 240 | 12 | _ | - | - |
| SX 270 | - | - | _ | 48 | 192 | 12 | 48 | 312 | 12 | 48 | 336 | 24 |
| SX 320 | - | - | _ | 48 | 192 | 12 | 48 | 312 | 12 | 48 | 336 | 24 |
| continued | | | | | | | | | | | | |

⁽⁸⁾ The number of GPIOs does not include transceiver I/Os. In the Intel Quartus Prime software, the number of user I/Os includes transceiver I/Os.

⁽⁹⁾ Each LVDS I/O pair can be used as differential input or output.



Types of Embedded Memory

The Intel Arria 10 devices contain two types of memory blocks:

- 20 Kb M20K blocks—blocks of dedicated memory resources. The M20K blocks are ideal for larger memory arrays while still providing a large number of independent ports.
- 640 bit memory logic array blocks (MLABs)—enhanced memory blocks that are configured from dual-purpose logic array blocks (LABs). The MLABs are ideal for wide and shallow memory arrays. The MLABs are optimized for implementation of shift registers for digital signal processing (DSP) applications, wide and shallow FIFO buffers, and filter delay lines. Each MLAB is made up of ten adaptive logic modules (ALMs). In the Intel Arria 10 devices, you can configure these ALMs as ten 32 x 2 blocks, giving you one 32 x 20 simple dual-port SRAM block per MLAB.

Embedded Memory Capacity in Intel Arria 10 Devices

| | Product | M2 | :0K | ML | AB | Total RAM Bit |
|-------------------|---------|-------|--------|--------|--------------|---------------|
| Variant | Line | | | Block | RAM Bit (Kb) | (Kb) |
| Intel Arria 10 GX | GX 160 | 440 | 8,800 | 1,680 | 1,050 | 9,850 |
| | GX 220 | 587 | 11,740 | 2,703 | 1,690 | 13,430 |
| | GX 270 | 750 | 15,000 | 3,922 | 2,452 | 17,452 |
| | GX 320 | 891 | 17,820 | 4,363 | 2,727 | 20,547 |
| | GX 480 | 1,431 | 28,620 | 6,662 | 4,164 | 32,784 |
| | GX 570 | 1,800 | 36,000 | 8,153 | 5,096 | 41,096 |
| | GX 660 | 2,131 | 42,620 | 9,260 | 5,788 | 48,408 |
| | GX 900 | 2,423 | 48,460 | 15,017 | 9,386 | 57,846 |
| | GX 1150 | 2,713 | 54,260 | 20,774 | 12,984 | 67,244 |
| Intel Arria 10 GT | GT 900 | 2,423 | 48,460 | 15,017 | 9,386 | 57,846 |
| | GT 1150 | 2,713 | 54,260 | 20,774 | 12,984 | 67,244 |
| Intel Arria 10 SX | SX 160 | 440 | 8,800 | 1,680 | 1,050 | 9,850 |
| | SX 220 | 587 | 11,740 | 2,703 | 1,690 | 13,430 |
| | SX 270 | 750 | 15,000 | 3,922 | 2,452 | 17,452 |
| | SX 320 | 891 | 17,820 | 4,363 | 2,727 | 20,547 |
| | SX 480 | 1,431 | 28,620 | 6,662 | 4,164 | 32,784 |
| | SX 570 | 1,800 | 36,000 | 8,153 | 5,096 | 41,096 |
| | SX 660 | 2,131 | 42,620 | 9,260 | 5,788 | 48,408 |

Table 18. Embedded Memory Capacity and Distribution in Intel Arria 10 Devices



Embedded Memory Configurations for Single-port Mode

Table 19. Single-port Embedded Memory Configurations for Intel Arria 10 Devices

This table lists the maximum configurations supported for single-port RAM and ROM modes.

| Memory Block | Depth (bits) | Programmable Width |
|--------------|--------------|--------------------|
| MLAB | 32 | x16, x18, or x20 |
| | 64 (10) | x8, x9, x10 |
| М20К | 512 | x40, x32 |
| | 1К | x20, x16 |
| | 2К | x10, x8 |
| | 4К | x5, x4 |
| | 8К | x2 |
| | 16К | ×1 |

Clock Networks and PLL Clock Sources

The clock network architecture is based on Intel's global, regional, and peripheral clock structure. This clock structure is supported by dedicated clock input pins, fractional clock synthesis PLLs, and integer I/O PLLs.

Clock Networks

The Intel Arria 10 core clock networks are capable of up to 800 MHz fabric operation across the full industrial temperature range. For the external memory interface, the clock network supports the hard memory controller with speeds up to 2,400 Mbps in a quarter-rate transfer.

To reduce power consumption, the Intel Quartus Prime software identifies all unused sections of the clock network and powers them down.

Fractional Synthesis and I/O PLLs

Intel Arria 10 devices contain up to 32 fractional synthesis PLLs and up to 16 I/O PLLs that are available for both specific and general purpose uses in the core:

- Fractional synthesis PLLs—located in the column adjacent to the transceiver blocks
- I/O PLLs—located in each bank of the 48 I/Os

Fractional Synthesis PLLs

You can use the fractional synthesis PLLs to:

- Reduce the number of oscillators that are required on your board
- Reduce the number of clock pins that are used in the device by synthesizing multiple clock frequencies from a single reference clock source

⁽¹⁰⁾ Supported through software emulation and consumes additional MLAB blocks.



The scalable hard IP supports multiple independent 10GbE ports while using a single PLL for all the 10GBASE-R PCS instantiations, which saves on core logic resources and clock networks:

- Simplifies multiport 10GbE systems compared to XAUI interfaces that require an external XAUI-to-10G PHY.
- Incorporates Electronic Dispersion Compensation (EDC), which enables direct connection to standard 10 Gbps XFP and SFP+ pluggable optical modules.
- Supports backplane Ethernet applications and includes a hard 10GBASE-KR Forward Error Correction (FEC) circuit that you can use for 10 Gbps and 40 Gbps applications.

The 10 Gbps Ethernet PCS hard IP and 10GBASE-KR FEC are present in every transceiver channel.

Related Information

PCS Features on page 30

Low Power Serial Transceivers

Intel Arria 10 FPGAs and SoCs include lowest power transceivers that deliver high bandwidth, throughput and low latency.

Intel Arria 10 devices deliver the industry's lowest power consumption per transceiver channel:

- 12.5 Gbps transceivers at as low as 242 mW
- 10 Gbps transceivers at as low as 168 mW
- 6 Gbps transceivers at as low as 117 mW

Intel Arria 10 transceivers support various data rates according to application:

- Chip-to-chip and chip-to-module applications—from 1 Gbps up to 25.8 Gbps
- Long reach and backplane applications—from 1 Gbps up to 12.5 with advanced adaptive equalization
- Critical power sensitive applications—from 1 Gbps up to 11.3 Gbps using lower power modes

The combination of 20 nm process technology and architectural advances provide the following benefits:

- Significant reduction in die area and power consumption
- Increase of up to two times in transceiver I/O density compared to previous generation devices while maintaining optimal signal integrity
- Up to 72 total transceiver channels—you can configure up to 6 of these channels to run as fast as 25.8 Gbps
- All channels feature continuous data rate support up to the maximum rated speed



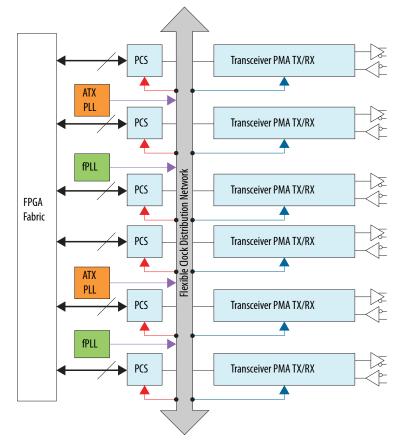


Figure 6. Intel Arria 10 Transceiver Block Architecture

Transceiver Channels

All transceiver channels feature a dedicated Physical Medium Attachment (PMA) and a hardened Physical Coding Sublayer (PCS).

- The PMA provides primary interfacing capabilities to physical channels.
- The PCS typically handles encoding/decoding, word alignment, and other preprocessing functions before transferring data to the FPGA core fabric.

A transceiver channel consists of a PMA and a PCS block. Most transceiver banks have 6 channels. There are some transceiver banks that contain only 3 channels.

A wide variety of bonded and non-bonded data rate configurations is possible using a highly configurable clock distribution network. Up to 80 independent transceiver data rates can be configured.

The following figures are graphical representations of top views of the silicon die, which correspond to reverse views for flip chip packages. Different Intel Arria 10 devices may have different floorplans than the ones shown in the figures.



Each transceiver channel contains a channel PLL that can be used as the CMU PLL or clock data recovery (CDR) PLL. In CDR mode, the channel PLL recovers the receiver clock and data in the transceiver channel. Up to 80 independent data rates can be configured on a single Intel Arria 10 device.

Table 23. PMA Features of the Transceivers in Intel Arria 10 Devices

| Feature | Capability |
|--|---|
| Chip-to-Chip Data Rates | 1 Gbps to 17.4 Gbps (Intel Arria 10 GX devices) 1 Gbps to 25.8 Gbps (Intel Arria 10 GT devices) |
| Backplane Support | Drive backplanes at data rates up to 12.5 Gbps |
| Optical Module Support | SFP+/SFP, XFP, CXP, QSFP/QSFP28, CFP/CFP2/CFP4 |
| Cable Driving Support | SFP+ Direct Attach, PCI Express over cable, eSATA |
| Transmit Pre-Emphasis | 4-tap transmit pre-emphasis and de-emphasis to compensate for system channel loss |
| Continuous Time Linear Equalizer (CTLE) | Dual mode, high-gain, and high-data rate, linear receive equalization to compensate for system channel loss |
| Decision Feedback Equalizer (DFE) | 7-fixed and 4-floating tap DFE to equalize backplane channel loss in the presence of crosstalk and noisy environments |
| Variable Gain Amplifier | Optimizes the signal amplitude prior to the CDR sampling and operates in fixed and adaptive modes |
| Altera Digital Adaptive Parametric Tuning (ADAPT) | Fully digital adaptation engine to automatically adjust all link equalization parameters— including CTLE, DFE, and variable gain amplifier blocks—that provide optimal link margin without intervention from user logic |
| Precision Signal Integrity Calibration Engine (PreSICE) | Hardened calibration controller to quickly calibrate all transceiver control parameters on power-up, which provides the optimal signal integrity and jitter performance |
| Advanced Transmit (ATX) PLL | Low jitter ATX (LC tank based) PLLs with continuous tuning range to cover a wide range of standard and proprietary protocols |
| Fractional PLLs | On-chip fractional frequency synthesizers to replace on-board crystal oscillators and reduce system cost |
| Digitally Assisted Analog CDR | Superior jitter tolerance with fast lock time |
| Dynamic Partial Reconfiguration | Allows independent control of the Avalon memory-mapped interface of each transceiver channel for the highest transceiver flexibility |
| Multiple PCS-PMA and PCS- PLD interface widths | 8-, 10-, 16-, 20-, 32-, 40-, or 64-bit interface widths for flexibility of deserialization width, encoding, and reduced latency |

PCS Features

This table summarizes the Intel Arria 10 transceiver PCS features. You can use the transceiver PCS to support a wide range of protocols ranging from 1 Gbps to 25.8 Gbps.



Table 24.Improvements in 20 nm HPS

This table lists the key improvements of the 20 nm HPS compared to the 28 nm HPS.

| Advantages/ Improvements | Description |
|---|--|
| Increased performance and overdrive capability | While the nominal processor frequency is 1.2 GHz, the 20 nm HPS offers an "overdrive" feature which enables a higher processor operating frequency. This requires a higher supply voltage value that is unique to the HPS and may require a separate regulator. |
| Increased processor memory bandwidth and DDR4 support | Up to 64-bit DDR4 memory at 2,400 Mbps support is available for the processor. The hard memory controller for the HPS comprises a multi-port front end that manages connections to a single port memory controller. The multi-port front end allows logic core and the HPS to share ports and thereby the available bandwidth of the memory controller. |
| Flexible I/O sharing | An advanced I/O pin muxing scheme allows improved sharing of I/O between the HPS and the core logic. The following types of I/O are available for SoC: 17 dedicated I/Os—physically located inside the HPS block and are not accessible to logic within the core. The 17 dedicated I/Os are used for HPS clock, resets, and interfacing with boot devices, QSPI, and SD/MMC. |
| | 48 direct shared I/O—located closest to the HPS block and are ideal for high speed HPS peripherals such as EMAC, USB, and others. There is one bank of 48 I/Os that supports direct sharing where the 48 I/Os can be shared 12 I/Os at a time. |
| | • Standard (shared) I/O—all standard I/Os can be shared by the HPS peripherals and any logic within the core. For designs where more than 48 I/Os are required to fully use all the peripherals in the HPS, these I/Os can be connected through the core logic. |
| EMAC core | Three EMAC cores are available in the HPS. The EMAC cores enable an application to support two redundant Ethernet connections; for example, backplane, or two EMAC cores for managing IEEE 1588 time stamp information while allowing a third EMAC core for debug and configuration. All three EMACs can potentially share the same time stamps, simplifying the 1588 time stamping implementation. A new serial time stamp interface allows core logic to access and read the time stamp values. The integrated EMAC controllers can be connected to external Ethernet PHY through the provided MDIO or I ² C interface. |
| On-chip memory | The on-chip memory is updated to 256 KB support and can support larger data sets and real time algorithms. |
| ECC enhancements | Improvements in L2 Cache ECC management allow identification of errors down to the address level. ECC enhancements also enable improved error injection and status reporting via the introduction of new memory mapped access to syndrome and data signals. |
| HPS to FPGA Interconnect Backbone | Although the HPS and the Logic Core can operate independently, they are tightly coupled via a high-bandwidth system interconnect built from high-performance ARM AMBA AXI bus bridges. IP bus masters in the FPGA fabric have access to HPS bus slaves via the FPGA-to-HPS interconnect. Similarly, HPS bus masters have access to bus slaves in the core fabric via the HPS-to-FPGA bridge. Both bridges are AMBA AXI-3 compliant and support simultaneous read and write transactions. Up to three masters within the core fabric can share the HPS SDRAM controller with the processor. Additionally, the processor can be used to configure the core fabric under program control via a dedicated 32-bit configuration port. |
| FPGA configuration and HPS booting | The FPGA fabric and HPS in the SoCs are powered independently. You can reduce the clock frequencies or gate the clocks to reduce dynamic power. You can configure the FPGA fabric and boot the HPS independently, in any order, providing you with more design flexibility. |
| Security | New security features have been introduced for anti-tamper management, secure boot, encryption (AES), and authentication (SHA). |



Features of the HPS

The HPS has the following features:

- 1.2-GHz, dual-core ARM Cortex-A9 MPCore processor with up to 1.5-GHz via overdrive
 - ARMv7-A architecture that runs 32-bit ARM instructions, 16-bit and 32-bit Thumb instructions, and 8-bit Java byte codes in Jazelle style
 - Superscalar, variable length, out-of-order pipeline with dynamic branch prediction
 - Instruction Efficiency 2.5 MIPS/MHz, which provides total performance of 7500 MIPS at 1.5 GHz
- Each processor core includes:
 - 32 KB of L1 instruction cache, 32 KB of L1 data cache
 - Single- and double-precision floating-point unit and NEON media engine
 - CoreSight debug and trace technology
 - Snoop Control Unit (SCU) and Acceleration Coherency Port (ACP)
- 512 KB of shared L2 cache
- 256 KB of scratch RAM
- Hard memory controller with support for DDR3, DDR4 and optional error correction code (ECC) support
- Multiport Front End (MPFE) Scheduler interface to the hard memory controller
- 8-channel direct memory access (DMA) controller
- QSPI flash controller with SIO, DIO, QIO SPI Flash support
- NAND flash controller (ONFI 1.0 or later) with DMA and ECC support, updated to support 8 and 16-bit Flash devices and new command DMA to offload CPU for fast power down recovery
- Updated SD/SDIO/MMC controller to eMMC 4.5 with DMA with CE-ATA digital command support
- 3 10/100/1000 Ethernet media access control (MAC) with DMA
- 2 USB On-the-Go (OTG) controllers with DMA
- 5 I²C controllers (3 can be used by EMAC for MIO to external PHY)
- 2 UART 16550 Compatible controllers
- 4 serial peripheral interfaces (SPI) (2 Master, 2 Slaves)
- 62 programmable general-purpose I/Os, which includes 48 direct share I/Os that allows the HPS peripherals to connect directly to the FPGA I/Os
- 7 general-purpose timers
- 4 watchdog timers
- Anti-tamper, Secure Boot, Encryption (AES) and Authentication (SHA)



FPGA Configuration and HPS Booting

The FPGA fabric and HPS in the SoC FPGA must be powered at the same time. You can reduce the clock frequencies or gate the clocks to reduce dynamic power.

Once powered, the FPGA fabric and HPS can be configured independently thus providing you with more design flexibility:

- You can boot the HPS independently. After the HPS is running, the HPS can fully or partially reconfigure the FPGA fabric at any time under software control. The HPS can also configure other FPGAs on the board through the FPGA configuration controller.
- Configure the FPGA fabric first, and then boot the HPS from memory accessible to the FPGA fabric.

Hardware and Software Development

For hardware development, you can configure the HPS and connect your soft logic in the FPGA fabric to the HPS interfaces using the Platform Designer system integration tool in the Intel Quartus Prime software.

For software development, the ARM-based SoC FPGA devices inherit the rich software development ecosystem available for the ARM Cortex-A9 MPCore processor. The software development process for Intel SoC FPGAs follows the same steps as those for other SoC devices from other manufacturers. Support for Linux*, VxWorks*, and other operating systems are available for the SoC FPGAs. For more information on the operating systems support availability, contact the Intel FPGA sales team.

You can begin device-specific firmware and software development on the Intel SoC FPGA Virtual Target. The Virtual Target is a fast PC-based functional simulation of a target development system—a model of a complete development board. The Virtual Target enables the development of device-specific production software that can run unmodified on actual hardware.

Dynamic and Partial Reconfiguration

The Intel Arria 10 devices support dynamic and partial reconfiguration. You can use dynamic and partial reconfiguration simultaneously to enable seamless reconfiguration of both the device core and transceivers.

Dynamic Reconfiguration

You can reconfigure the PMA and PCS blocks while the device continues to operate. This feature allows you to change the data rates, protocol, and analog settings of a channel in a transceiver bank without affecting on-going data transfer in other transceiver banks. This feature is ideal for applications that require dynamic multiprotocol or multirate support.

Partial Reconfiguration

Using partial reconfiguration, you can reconfigure some parts of the device while keeping the device in operation.



Instead of placing all device functions in the FPGA fabric, you can store some functions that do not run simultaneously in external memory and load them only when required. This capability increases the effective logic density of the device, and lowers cost and power consumption.

In the Intel solution, you do not have to worry about intricate device architecture to perform a partial reconfiguration. The partial reconfiguration capability is built into the Intel Quartus Prime design software, making such time-intensive task simple.

Intel Arria 10 devices support partial reconfiguration in the following configuration options:

- Using an internal host:
 - All supported configuration modes where the FPGA has access to external memory devices such as serial and parallel flash memory.
 - Configuration via Protocol [CvP (PCIe)]
- Using an external host—passive serial (PS), fast passive parallel (FPP) x8, FPP x16, and FPP x32 I/O interface.

Enhanced Configuration and Configuration via Protocol

Table 25. Configuration Schemes and Features of Intel Arria 10 Devices

Intel Arria 10 devices support 1.8 V programming voltage and several configuration schemes.

| Scheme | Data Width | Max Clock Rate (MHz) | Max Data Rate (Mbps) (13) | Decompression | Design Security ⁽¹ 4) | Partial Reconfiguration (15) | Remote System Update |
|--|------------------|----------------------------|------------------------------------|---------------|--|------------------------------------|---|
| JTAG | 1 bit | 33 | 33 | _ | - | Yes ⁽¹⁶⁾ | - |
| Active Serial (AS) through the EPCQ-L configuration device | 1 bit, 4 bits | 100 | 400 | Yes | Yes | Yes ⁽¹⁶⁾ | Yes |
| Passive serial (PS) through CPLD or external microcontroller | 1 bit | 100 | 100 | Yes | Yes | Yes ⁽¹⁶⁾ | Parallel Flash Loader (PFL) IP core |
| continued | | | | ntinued | | | |

⁽¹³⁾ Enabling either compression or design security features affects the maximum data rate. Refer to the Intel Arria 10 Device Datasheet for more information.

⁽¹⁴⁾ Encryption and compression cannot be used simultaneously.

⁽¹⁵⁾ Partial reconfiguration is an advanced feature of the device family. If you are interested in using partial reconfiguration, contact Intel for support.

⁽¹⁶⁾ Partial configuration can be performed only when it is configured as internal host.



| Scheme | Data Width | Max Clock Rate (MHz) | Max Data Rate (Mbps) (13) | Decompression | Design Security ⁽¹ 4) | Partial Reconfiguration (15) | Remote System Update |
|--|----------------------------|----------------------------|------------------------------------|---------------|--|------------------------------------|----------------------------|
| Fast passive | 8 bits | 100 | 3200 | Yes | Yes | Yes ⁽¹⁷⁾ | PFL IP |
| parallel (FPP) through CPLD or external microcontroller | 16 bits | | | Yes | Yes | - | core |
| | 32 bits | | | Yes | Yes | | |
| Configuration via | 16 bits | 100 | 3200 | Yes | Yes | Yes ⁽¹⁷⁾ | _ |
| HPS | 32 bits | | | Yes | Yes | | |
| Configuration via Protocol [CvP (PCIe*)] | x1, x2, x4, x8 lanes | - | 8000 | Yes | Yes | Yes ⁽¹⁶⁾ | _ |

You can configure Intel Arria 10 devices through PCIe using Configuration via Protocol (CvP). The Intel Arria 10 CvP implementation conforms to the PCIe 100 ms power-up-to-active time requirement.

SEU Error Detection and Correction

Intel Arria 10 devices offer robust and easy-to-use single-event upset (SEU) error detection and correction circuitry.

The detection and correction circuitry includes protection for Configuration RAM (CRAM) programming bits and user memories. The CRAM is protected by a continuously running CRC error detection circuit with integrated ECC that automatically corrects one or two errors and detects higher order multi-bit errors. When more than two errors occur, correction is available through reloading of the core programming file, providing a complete design refresh while the FPGA continues to operate.

The physical layout of the Intel Arria 10 CRAM array is optimized to make the majority of multi-bit upsets appear as independent single-bit or double-bit errors which are automatically corrected by the integrated CRAM ECC circuitry. In addition to the CRAM protection, the M20K memory blocks also include integrated ECC circuitry and are layout-optimized for error detection and correction. The MLAB does not have ECC.

Power Management

Intel Arria 10 devices leverage the advanced 20 nm process technology, a low 0.9 V core power supply, an enhanced core architecture, and several optional power reduction techniques to reduce total power consumption by as much as 40% compared to Arria V devices and as much as 60% compared to Stratix V devices.

⁽¹³⁾ Enabling either compression or design security features affects the maximum data rate. Refer to the Intel Arria 10 Device Datasheet for more information.

⁽¹⁴⁾ Encryption and compression cannot be used simultaneously.

⁽¹⁵⁾ Partial reconfiguration is an advanced feature of the device family. If you are interested in using partial reconfiguration, contact Intel for support.

⁽¹⁷⁾ Supported at a maximum clock rate of 100 MHz.



The optional power reduction techniques in Intel Arria 10 devices include:

- SmartVID—a code is programmed into each device during manufacturing that allows a smart regulator to operate the device at lower core V_{CC} while maintaining performance
- **Programmable Power Technology**—non-critical timing paths are identified by the Intel Quartus Prime software and the logic in these paths is biased for low power instead of high performance
- Low Static Power Options—devices are available with either standard static power or low static power while maintaining performance

Furthermore, Intel Arria 10 devices feature Intel's industry-leading low power transceivers and include a number of hard IP blocks that not only reduce logic resources but also deliver substantial power savings compared to soft implementations. In general, hard IP blocks consume up to 90% less power than the equivalent soft logic implementations.

Incremental Compilation

The Intel Quartus Prime software incremental compilation feature reduces compilation time and helps preserve performance to ease timing closure. The incremental compilation feature enables the partial reconfiguration flow for Intel Arria 10 devices.

Incremental compilation supports top-down, bottom-up, and team-based design flows. This feature facilitates modular, hierarchical, and team-based design flows where different designers compile their respective design sections in parallel. Furthermore, different designers or IP providers can develop and optimize different blocks of the design independently. These blocks can then be imported into the top level project.

Document Revision History for Intel Arria 10 Device Overview

| Document Version | Changes |
|---------------------|--|
| 2018.04.09 | Updated the lowest V_{CC} from 0.83 V to 0.82 V in the topic listing a summary of the device features. |

| Date | Version | Changes |
|--------------|------------|--|
| January 2018 | 2018.01.17 | • Updated the maximum data rate for HPS (Intel Arria 10 SX devices external memory interface DDR3 controller from 2,166 Mbps to 2,133 Mbps. |
| | | Updated maximum frequency supported for half rate QDRII and QDRII + SRAM to 633 MHz in <i>Memory Standards Supported by the Soft</i> <i>Memory Controller</i> table. |
| | | Updated transceiver backplane capability to 12.5 Gbps. |
| | | • Removed transceiver speed grade 5 in <i>Sample Ordering Core and Available Options for Intel Arria 10 GX Devices</i> figure. |
| | 1 | continued |

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| September 2017 July 2017 July 2017 May 2017 May 2017 March 2017 | 2017.09.20 2017.07.13 2017.07.06 2017.05.08 | Removed package code 40, low static power, SmartVID, industrial, and military operating temperature support from <i>Sample Ordering Core and Available Options for Intel Arria 10 GT Devices</i> figure. Updated short reach transceiver rate for Intel Arria 10 GT devices to 25.8 Gbps. Removed On-Die Instrumentation — EyeQ and Jitter Margin Tool support from <i>PMA Features of the Transceivers in Intel Arria 10 Devices</i> table. Updated the maximum speed of the DDR4 external memory interface from 1,333 MHz/2,666 Mbps to 1,200 MHz/2,400 Mbps. Corrected the automotive temperature range in the figure showing the available options for the Intel Arria 10 GX devices from "-40°C to 100°C" to "-40°C to 125°C". Added automotive temperature option to Intel Arria 10 GX device family. Corrected protocol names with "1588" to "IEEE 1588v2". Updated the vertical migration table to remove vertical migration between Intel Arria 10 GX and Intel Arria 10 SX device variants. |
|--|--|--|
| July 2017 July 2017 May 2017 | 2017.07.13 2017.07.06 2017.05.08 | 1,333 MHz/2,666 Mbps to 1,200 MHz/2,400 Mbps. Corrected the automotive temperature range in the figure showing the available options for the Intel Arria 10 GX devices from "-40°C to 100°C" to "-40°C to 125°C". Added automotive temperature option to Intel Arria 10 GX device family. Corrected protocol names with "1588" to "IEEE 1588v2". Updated the vertical migration table to remove vertical migration |
| July 2017 May 2017 | 2017.07.06 2017.05.08 | available options for the Intel Arria 10 GX devices from "-40°C to 100°C" to "-40°C to 125°C". Added automotive temperature option to Intel Arria 10 GX device family. Corrected protocol names with "1588" to "IEEE 1588v2". Updated the vertical migration table to remove vertical migration |
| May 2017 | 2017.05.08 | Corrected protocol names with "1588" to "IEEE 1588v2". Updated the vertical migration table to remove vertical migration |
| | | Updated the vertical migration table to remove vertical migration |
| March 2017 | | Removed all "Preliminary" marks. |
| | 2017.03.15 | Removed the topic about migration from Intel Arria 10 to Intel Stratix 10 devices. Rebranded as Intel. |
| October 2016 | 2016.10.31 | Removed package F36 from Intel Arria 10 GX devices. Updated Intel Arria 10 GT sample ordering code and maximum GX transceiver count. Intel Arria 10 GT devices are available only in the SF45 package option with a maximum of 72 transceivers. |
| May 2016 | 2016.05.02 | Updated the FPGA Configuration and HPS Booting topic. Remove V_{CC} PowerManager from the Summary of Features, Power Management and Arria 10 Device Variants and packages topics. This feature is no longer supported in Arria 10 devices. Removed LPDDR3 from the Memory Standards Supported by the HPS Hard Memory Controller table in the Memory Standards Supported by Intel Arria 10 Devices topic. This standard is only supported by the FPGA. Removed transceiver speed grade 5 from the Device Variants and Packages topic for Arria 10 GX and SX devices. |
| February 2016 | 2016.02.11 | Changed the maximum Arria 10 GT datarate to 25.8 Gbps and the minimum datarate to 1 Gbps globally. Revised the state for Core clock networks in the Summary of Features topic. Changed the transceiver parameters in the "Summary of Features for Arria 10 Devices" table. Changed the transceiver parameters in the "Maximum Resource Counts for Arria 10 GT Devices" table. Changed the package availability for GT devices in the "Package Plan for Arria 10 GT Devices" table. Changed the package configurations for GT devices in the "Migration Capability Across Arria 10 Product Lines" figure. Changed the transceiver parameters in the "Low Power Serial Transceivers" section. Changed the transceiver descriptions in the "Device Variants for the Arria 10 Device Family" table. Changed the "Sample Ordering Code and Available Options for Arria 10 GT Devices" figure. Changed the datarates for GT devices in the "PMA Features" section. Changed the datarates for GT devices in the "PCS Features" section. |

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| Date | Version | Changes |
|----------------|------------|---|
| December 2015 | 2015.12.14 | • Updated the number of M20K memory blocks for Arria 10 GX 660 from 2133 to 2131 and corrected the total RAM bit from 48,448 Kb to 48,408 Kb. |
| | | Corrected the number of DSP blocks for Arria 10 GX 660 from 1688 to 1687 in the table listing floating-point arithmetic resources. |
| November 2015 | 2015.11.02 | • Updated the maximum resources for Arria 10 GX 220, GX 320, GX 480, GX 660, SX 220, SX 320, SX 480, and SX 660. |
| | | Updated resource count for Arria 10 GX 320, GX 480, GX 660, SX 320, SX 480, a SX 660 devices in Number of Multipliers in Intel Arria 10 Devices table. |
| | | Updated the available options for Arria 10 GX, GT, and SX.Changed instances of <i>Quartus II</i> to <i>Quartus Prime</i>. |
| June 2015 | 2015.06.15 | Corrected label for Intel Arria 10 GT product lines in the vertical migration figure. |
| May 2015 | 2015.05.15 | Corrected the DDR3 half rate and quarter rate maximum frequencies in the table that lists the memory standards supported by the Intel Arria 10 hard memory controller. |
| May 2015 | 2015.05.04 | Added support for 13.5G JESD204b in the Summary of Features table. Added a link to Arria 10 GT Channel Usage in the Arria 10 GT Package Plan topic. |
| | | Added a note to the table, Maximum Resource Counts for Arria 10 GT devices. |
| | | Updated the power requirements of the transceivers in the Low Power Serial Transceivers topic. |
| January 2015 | 2015.01.23 | Added floating point arithmetic features in the Summary of Features table. |
| | | • Updated the total embedded memory from 38.38 megabits (Mb) to 65.6 Mb. |
| | | Updated the table that lists the memory standards supported by Intel Arria 10 devices. |
| | | Removed support for DDR3U, LPDDR3 SDRAM, RLDRAM 2, and DDR2. Moved RLDRAM 3 support from hard memory controller to soft memory controller. RLDRAM 3 support uses hard PHY with soft memory controller. |
| | | Added soft memory controller support for QDR IV. |
| | | • Updated the maximum resource count table to include the number of hard memory controllers available in each device variant. |
| | | • Updated the transceiver PCS data rate from 12.5 Gbps to 12 Gbps. |
| | | Updated the max clock rate of PS, FPP x8, FPP x16, and Configuration via HPS from 125 MHz to 100 MHz. |
| | | Added a feature for fractional synthesis PLLs: PLL cascading. |
| | | Updated the HPS programmable general-purpose I/Os from 54 to 62. |
| September 2014 | 2014.09.30 | • Corrected the 3 V I/O and LVDS I/O counts for F35 and F36 packages of Arria 10 GX. |
| | | • Corrected the 3 V I/O, LVDS I/O, and transceiver counts for the NF40 package of the Arria GX 570 and 660. |
| | | Removed 3 V I/O, LVDS I/O, and transceiver counts for the NF40 package of the Arria GX 900 and 1150. The NF40 package is not available for Arria 10 GX 900 and 1150. |
| | | continued |

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| Date | Version | Changes |
|---------------|------------|--|
| August 2014 | 2014.08.18 | Updated Memory (Kb) M20K maximum resources for Arria 10 GX 660 devices from 42,660 to 42,620. |
| | | Added GPIO columns consisting of LVDS I/O Bank and 3V I/O Bank in the Package Plan table. |
| | | • Added how to use memory interface clock frequency higher than 533 MHz in the I/O vertical migration. |
| | | Added information to clarify that RLDRAM3 support uses hard PHY with soft memory controller. |
| | | Added variable precision DSP blocks support for floating-point arithmetic. |
| June 2014 | 2014.06.19 | Updated number of dedicated I/Os in the HPS block to 17. |
| February 2014 | 2014.02.21 | Updated transceiver speed grade options for GT devices in Figure 2. |
| February 2014 | 2014.02.06 | Updated data rate for Arria 10 GT devices from 28.1 Gbps to 28.3 Gbps. |
| December 2013 | 2013.12.10 | Updated the HPS memory standards support from LPDDR2 to LPDDR3. Updated HPS block diagram to include dedicated HPS I/O and FPGA Configuration blocks as well as repositioned SD/SDIO/MMC, DMA, SPI and NAND Flash with ECC blocks . |
| December 2013 | 2013.12.02 | Initial release. |